

EIA ENGINEERING BULLETIN

**Diminishing Manufacturing Sources
and Material Shortages (DMSMS)
Management Practices**

GEB1

WORK IN PROGRESS

**ELECTRONIC INDUSTRIES ALLIANCE
GOVERNMENT ELECTRONICS AND
INFORMATION TECHNOLOGY ASSOCIATION
ENGINEERING DEPARTMENT**



A SECTOR OF



DMSMS Conference 2000

**Scott A. Hatch
Sanders**

LOCKHEED MARTIN



**Scott.A.Hatch@lmco.com
(603) 885-5119**

EIA GEB1: DMSMS Management Practices

EIA ENGINEERING BULLETIN

Diminishing Manufacturing Sources
and Material Shortages (DMSMS)
Management Practices

GEB1

WORK IN PROGRESS

ELECTRONIC INDUSTRIES ALLIANCE
GOVERNMENT ELECTRONICS AND
INFORMATION TECHNOLOGY ASSOCIATION
ENGINEERING DEPARTMENT

 A SECTOR OF


Electronic Industries Alliance

- Provide guidance for Military / Aerospace OEMs
- Incorporate Current Industry Methodologies
- Address DMSMS Mitigation Throughout Equipment Life
- Emphasize proactive DMSMS mitigation approaches

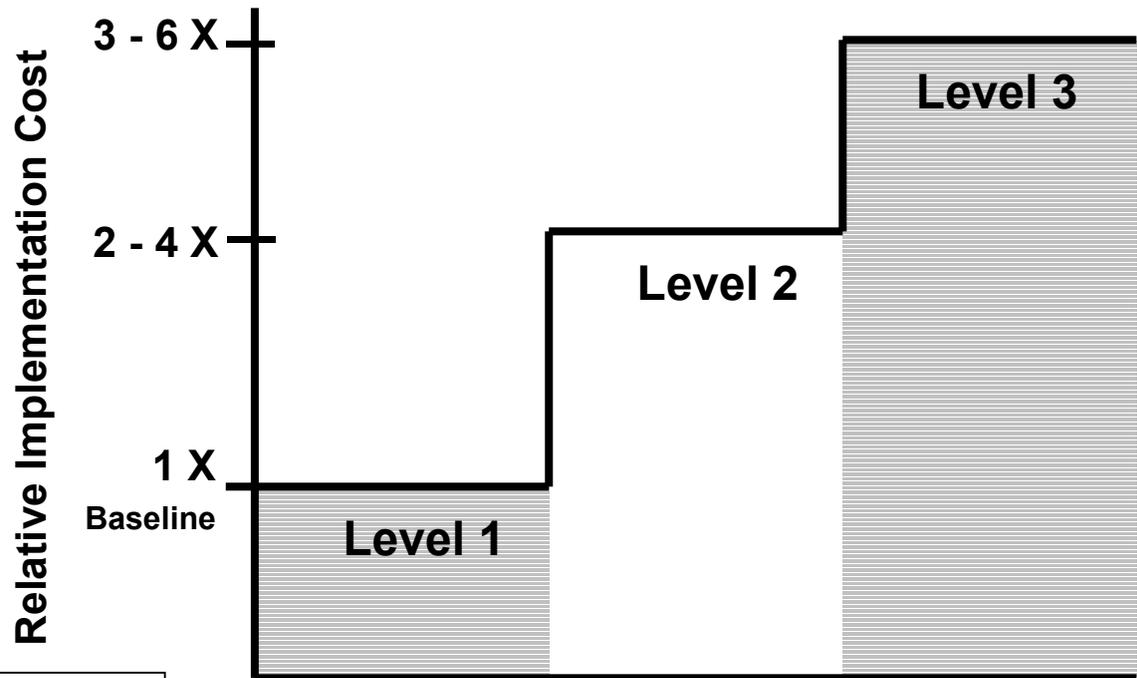
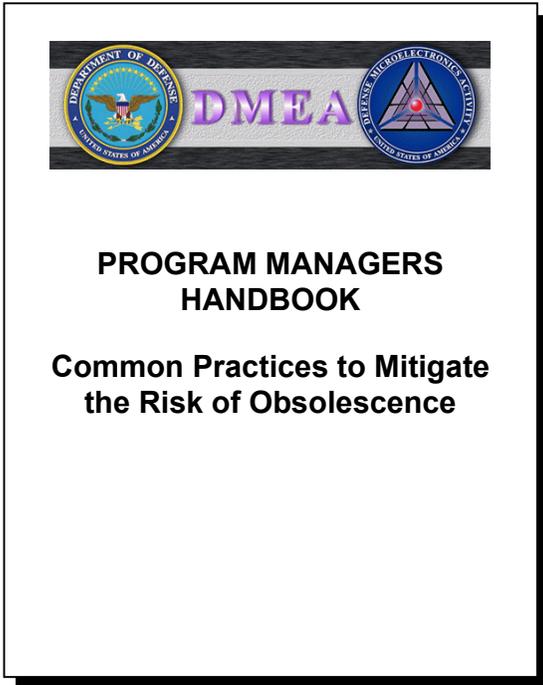


EIA GEB1: DMSMS Management Practices



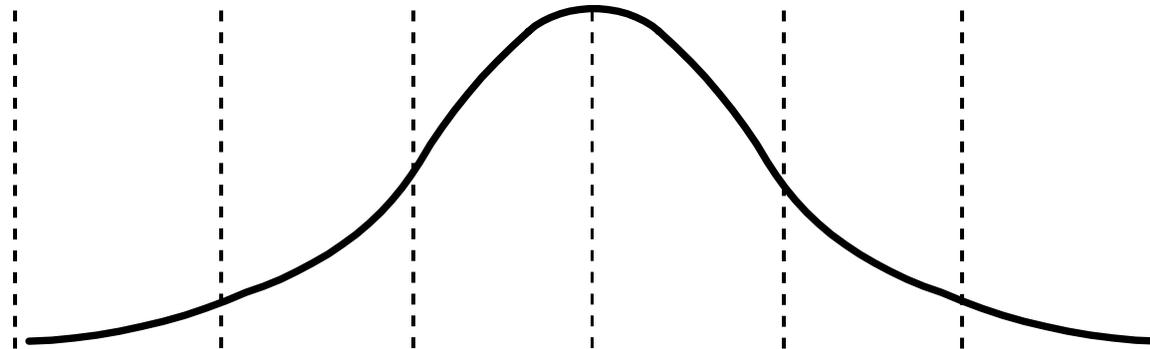
- Derived from several Industry and Government sources
- Compiled practices shown to be useful and are used by Industry at large

GEB1 Compliments The Program Managers Handbook



Trunnell, W. (DMEA). "A Summary of the Program Managers Handbook." Proceedings of DMSMS Conference 2000. <http://smaplab.ri.uah.edu/dmsms2k/> (23 Aug. 2000).

ANSI/EIA-724-97 Product Life Cycle Data Model



	Stage 1 Introduction	Stage 2 Growth	Stage 3 Maturity	Stage 4 Saturation	Stage 5 Decline	Stage 6 Phase-Out
Sales	Slow increase	Increasing rapidly	Stable	Leveling out	Decreasing	Lifetime buys offered
Price	Highest	Declining	Stable	Stable	Rising	High
Usage	Low	Increasing	Stable	Stable	Decreasing	Decreasing
Part Modification¹	Frequent	Major	Periodic changes	Few	Few or none	None
Competitors	Few	High	Stable number	Decline begins	Declining	Declining
Manufacturer profit	Low	Increasing	Stable	Stable	Reasonable for survivors	Reasonable for survivors (aftermarket)

1. Die shrink, mask change, etc.



Microcircuit Life Cycles & Introduction Rates

Average Microcircuit Life Span

Total (all quality ranges)	10 years
Military	> 12.5 years
Commercial	< 8.5 years
Certain Linear	< 14.5 years
Some uP, memories	< 5 years

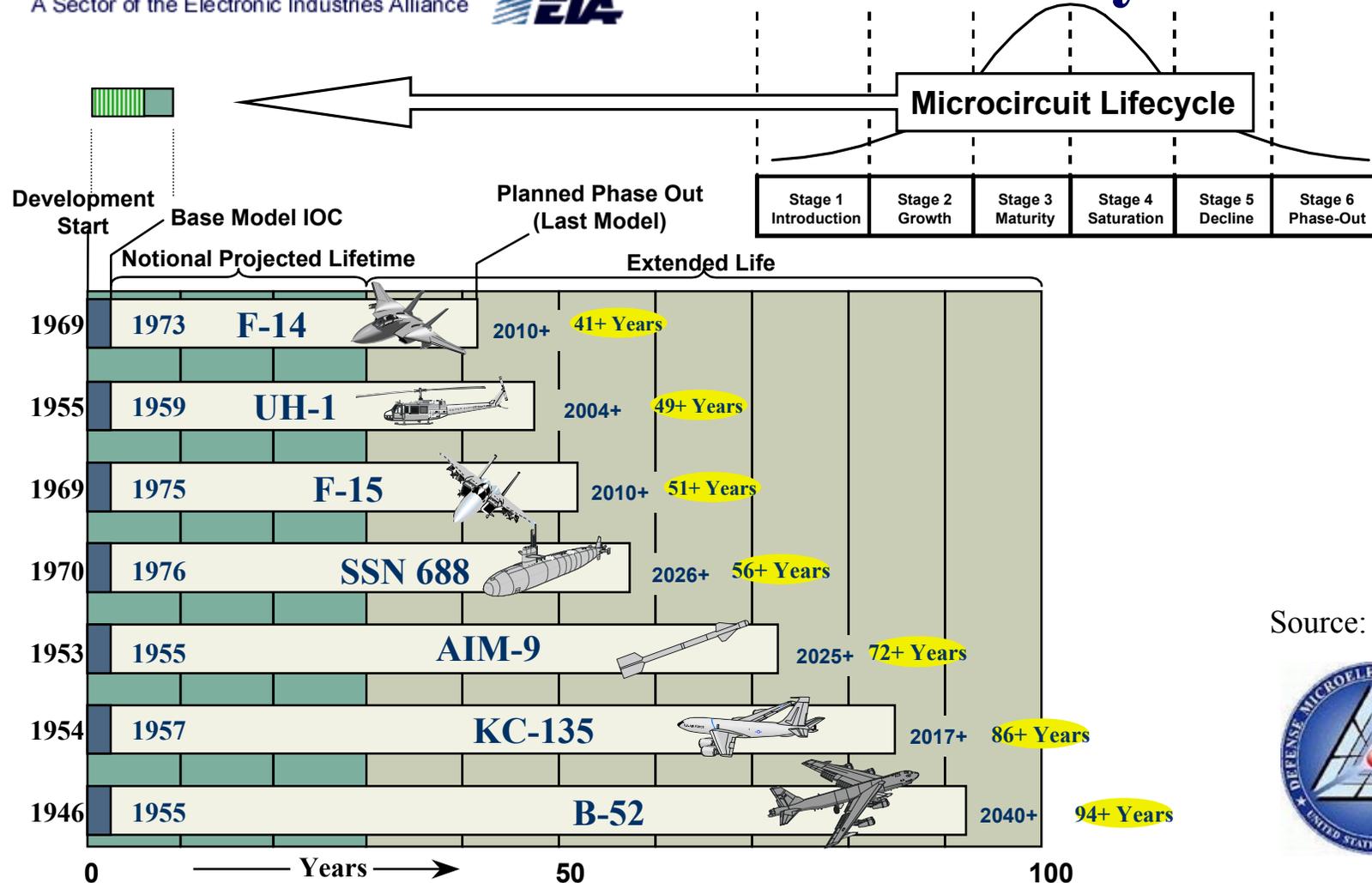


<u>Device Category</u>	<u>Average Introduction Rate</u>
Logic Families	6 years
Memory Families	9 months
Microprocessors	2 years
DSP	3 years
PLD	1 year
Linear Interfaces	8 years
Gate Arrays	2 years

Bick, E. (TACTech Inc.). "New & Improved Life Cycle Codes Updates - Response To AIM Users Regarding The New & Improved LCCs." ebick@tactech.com (20 Jul. 1999).

TACTech Inc. "Obsolescence Management In the Year 2000." 28 Oct. 1998. ftp://tactech.com/pub/overview.exe (14 Jun. 2000).

Weapon System Life Cycle



Source: DMEA



System Life Cycle Vs. Mitigation Approach

Planning for system upgrades in Phase I & II based upon Technology Insertion Solution

Bridge buy to support production until redesign available

Reclamation typically a last resort

		Phase 0	Phase I	Phase II	Phase III
		Concept Exploration	Program Definition and Risk Reduction	EMD / LRIP	Production, Fielding / Deployment, & Operational Support
Proactive DMSMS Mitigation Approaches (4.1)	Technology Road Mapping	X	X	X	X
	Planned System Upgrade ₁		X	X	X
	Technology Insertion ₁	X	X	X	X
	Technology Transparency	X	X	X	X
	Life Cycle Analysis / DMSMS Monitoring		X	X	X
Response to DMSMS Events (4.2)	Alternate Source			X	X
	Substitution			X	X
	Emulation				X
	Life of Type Buy ₂			X	X
	Redesign / Design Modification ₂			X	X
	Reverse Engineering				X
	Reclamation ₃				X

Technology Roadmapping



CRITICAL



Phase I: Preliminary Activity

1. Satisfy essential conditions
2. Provide leadership/sponsorship
3. Define the scope and boundaries for technology roadmap

Phase II: Development of the Technology Roadmap

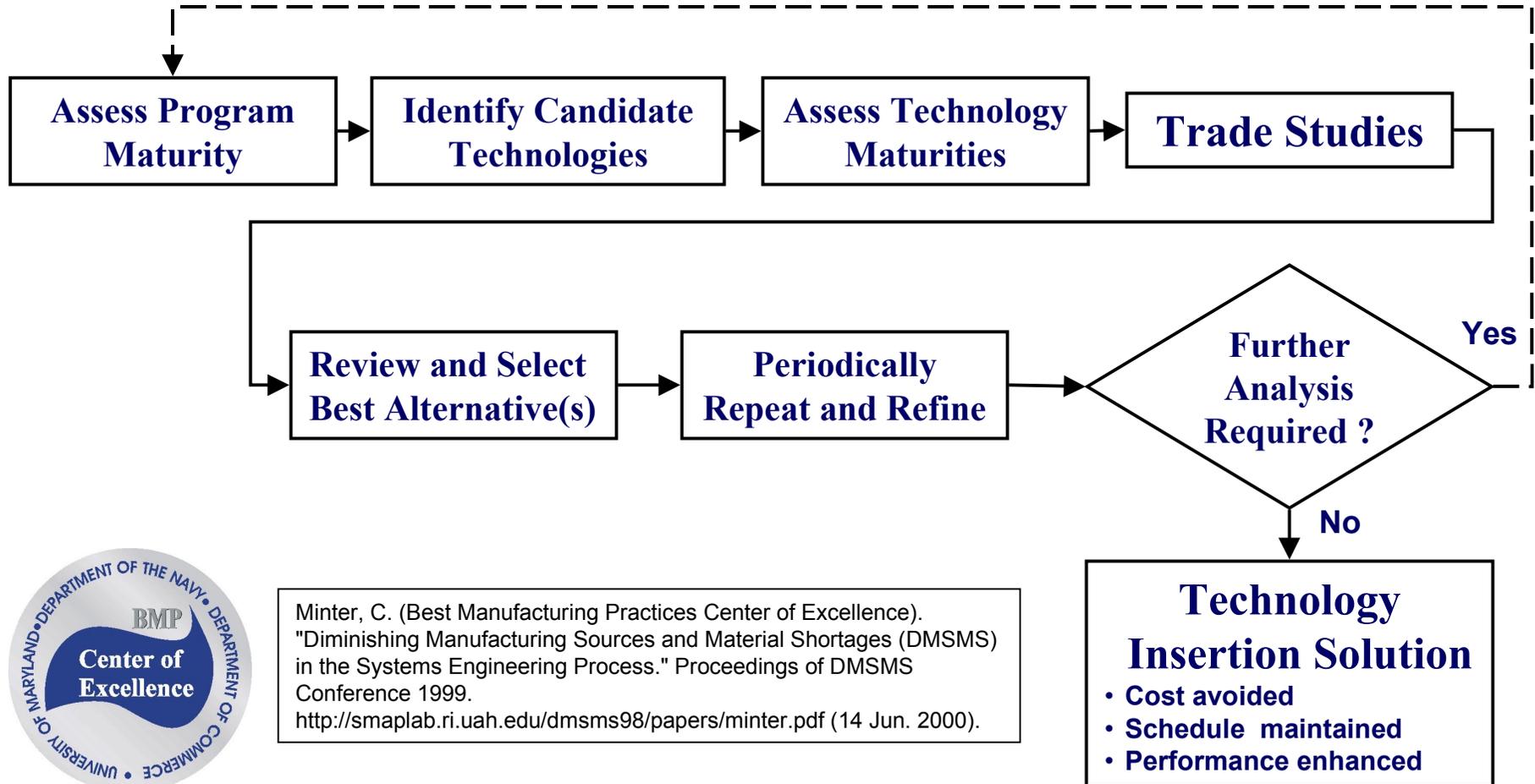
1. Identify the "product" that will be the focus of the roadmap
2. Identify the critical system requirements and their targets
3. Specify the major technology areas
4. Specify the technology drivers and their targets
5. Identify technology alternatives and their time lines
6. Recommend the technology alternatives that should be pursued
7. Create the technology roadmap report

Phase III: Follow-Up Activity

1. Critique and validate the roadmap
2. Develop an implementation plan

Bray, O.H.; Garcia, M.L. "Technology roadmapping: the integration of strategic and technology planning for competitiveness," Innovation in Technology Management - The Key to Global Leadership. PICMET '97: Portland International Conference on Management and Technology, 1997, IEEE, pp.25-28

Technology Insertion

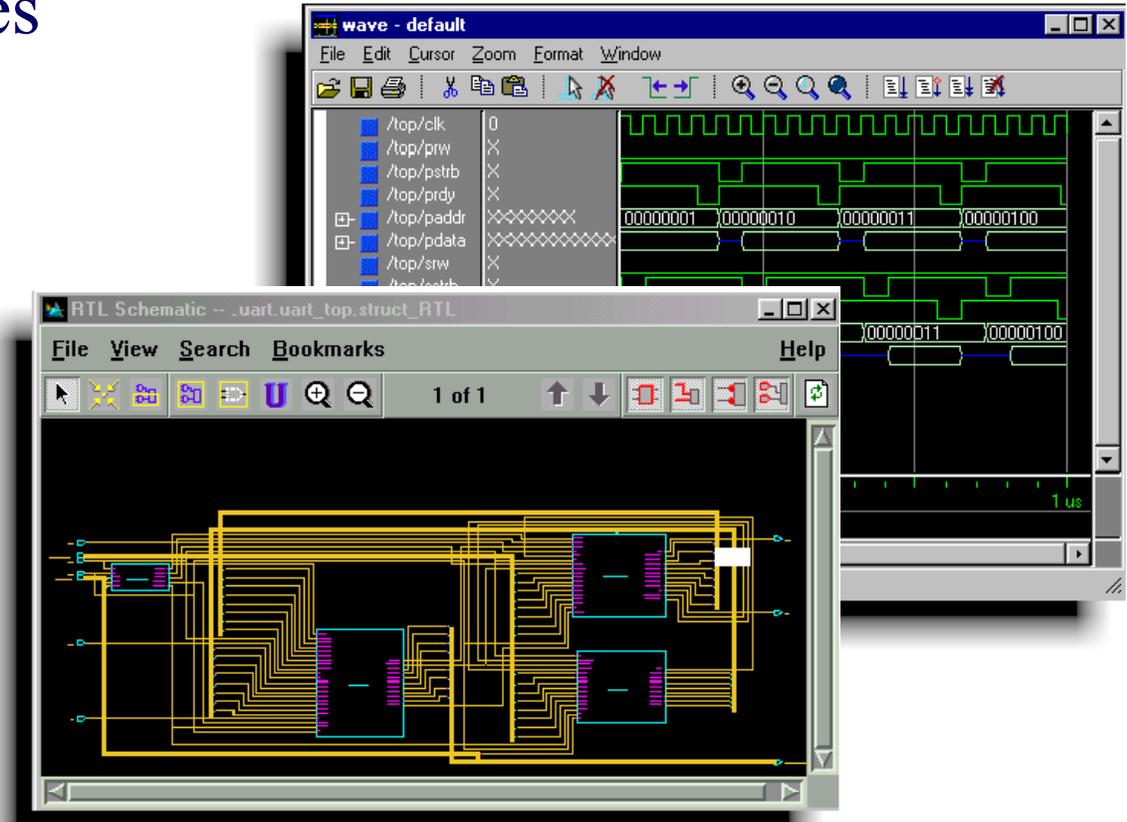


Minter, C. (Best Manufacturing Practices Center of Excellence). "Diminishing Manufacturing Sources and Material Shortages (DMSMS) in the Systems Engineering Process." Proceedings of DMSMS Conference 1999. <http://smaplab.ri.uah.edu/dmsms98/papers/minter.pdf> (14 Jun. 2000).

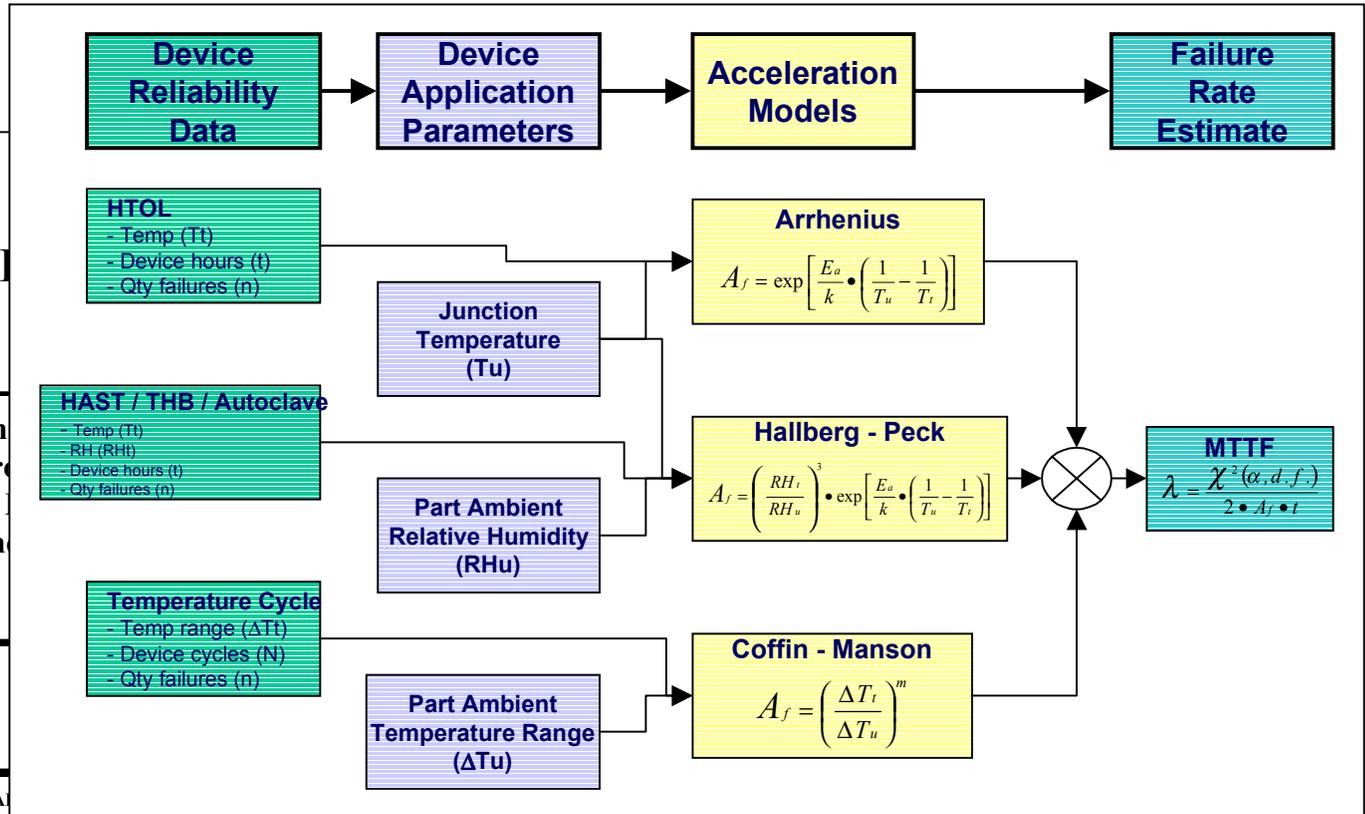


Technology Transparency

- Standard Interfaces
- VHDL
- Programmable Logic Devices



EIA SSB-1 Guidelines for Using PEMS



EIA ENGINEERING BULLETIN

Guidelines for Using Encapsulated Micro Semiconductors in Aerospace and Other Applications

SSB-1-B

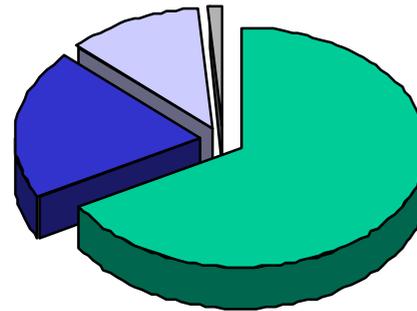
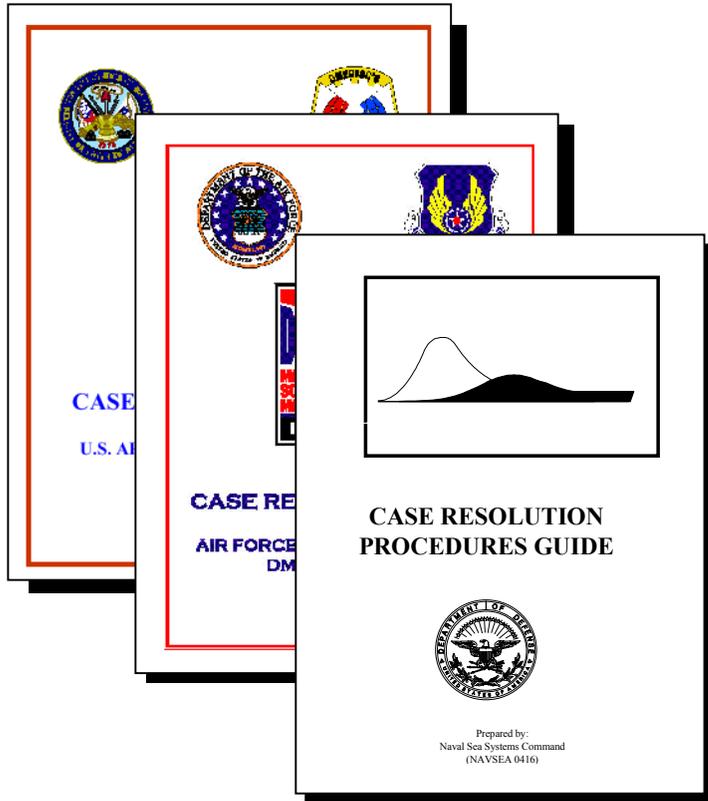
NOVEMBER 1999

ELECTRONIC INDUSTRIES ALLIANCE
GOVERNMENT ELECTRONICS AND
INFORMATION TECHNOLOGY ASSOCIATION
ENGINEERING DEPARTMENT



Livingston, H. (GEIA). "SSB-1: Guidelines for Using Plastic Encapsulated Microcircuits and Semiconductors in Military, Aerospace and Other Rugged Applications ." Proceedings of DMSMS Conference 2000. <http://smaplabb.ri.uah.edu/dmsms2k/> (24 Aug. 2000).

Responses to DMSMS Events



- Replacement Part (67%)
- Life-of-Type Buy (20%)
- Bridge Buy / Redesign (12%)
- Emulation (1%)



Porter, G.Z. (Boeing Commercial Aircraft Company) "Strategies for Obsolescence Management in the New Millennium." Proceedings of DMSMS Conference 1999. <http://smaplab.ri.uah.edu/dmsms98/presentations/porter.pdf> (14 Jun. 2000).

Nonrecurring Engineering Resolution Cost Factors

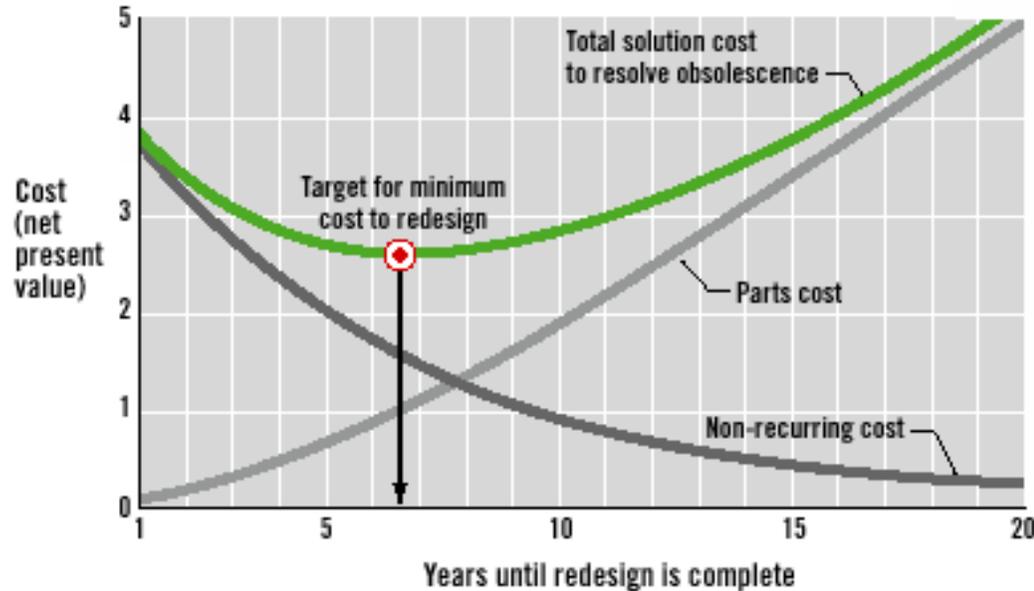
Resolution	Low	Average	High
Existing Stock	\$ 0	\$ 0	\$ 0
Reclamation	\$ 629	\$ 1,884	\$ 3,249
Alternate	\$ 2,750	\$ 6,384	\$ 16,500
Substitute	\$ 5,000	\$ 18,111	\$ 50,276
Aftermarket	\$ 15,390	\$ 47,360	\$ 114,882
Emulation	\$ 17,000	\$ 68,012	\$ 150,000
Redesign— Minor	\$ 22,400	\$ 111,034	\$ 250,000
Redesign— Major	\$ 200,000	\$ 410,152	\$ 770,000
Life of Type (LOT) Buy	*	*	*

* The LOT buy resolution is program-specific and should be calculated by the individual DoD programs.

Defense Microelectronics Activity (DMEA). "Resolution Cost Factors For Diminishing Manufacturing Sources And Material Shortages." May 1999. http://www.dmea.osd.mil/dms_area.html (14 Jun. 2000).



Economic Method for Evaluating DMSMS Solutions



- **"Redesign Cost"**
If the redesign can be deferred to a future year, the net present value of the redesign cost decreases.
- **"Parts Cost"**
As redesign is deferred, more parts need to be purchased to support production and repairs of the current design.

- **"Total Solution Cost"**

The sum of the two curves is the Total Solution Cost for a redesign in a particular future year.



Porter, G.Z. (Boeing Commercial Aircraft Company). "An Economic Method for Evaluating Electronic Component Obsolescence Solutions." May 1998.
<http://www.gidep.corona.navy.mil/dmsms/library/zell.pdf> (14 Jun. 2000).

EIA ENGINEERING BULLETIN

**Diminishing Manufacturing Sources
and Material Shortages (DMSMS)
Management Practices**

GEB1 

WORK IN PROGRESS

**ELECTRONIC INDUSTRIES ALLIANCE
GOVERNMENT ELECTRONICS AND
INFORMATION TECHNOLOGY ASSOCIATION
ENGINEERING DEPARTMENT**



A SECTOR OF



Feedback with narrative content is welcome:

- Working draft iterations through October
- Ballot GEB1 through GEIA in November
- Complete GEB1 for release in January 2001

Contact ...

Henry Livingston

Henry.C.Livingston@lmco.com

(603) 885-2360

or

Scott A. Hatch

Scott.A.Hatch@lmco.com

(603) 885-5119



G-12 Solid State Devices Committee

The G-12 Committee develops solutions to technical problems in the application, standardization, and reliability of solid state devices. This is implemented by evaluation and preparation of recommendations for specifications, standards, and other documents, both government and industry, to assure that solid state devices are suitable for their intended purposes. The G-12 Committee holds three regular meetings a year in conjunction with JEDEC JC-13.

For more information, see ...

<http://www.geia.org/eoc/G12/>



Task Group Members

Henry Livingston	Sanders, a Lockheed Martin Company (Chair)
Tom Dean	Boeing ISDS
Kevin Rankin	Defense Microelectronics Activity
Ron Shimazu	Defense Microelectronics Activity
Mike Jones	Defense Supply Center Columbus
Jack Tarsa	General Dynamics Defense Systems
Bahig Tawfellos	Honeywell International Defense & Space Systems
Lee Mathiesen	Lansdale Semiconductor
Paul Kelley	Litton Aero Products
Vernon Singleton	Lockheed Martin Federal Systems
Frances Crull	Northrop Grumman, ESSD
Keith Meyer	NWSC DMS Technology Center
Wes Hubbell	Raytheon
John Nirschl	Rockwell Collins
Scott Hatch	Sanders, a Lockheed Martin Company
Justine Corby	Sarnoff Corporation